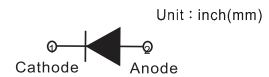
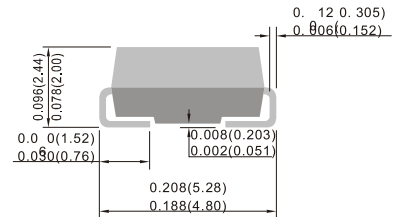
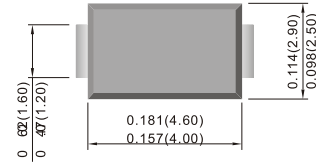


## Surface Mount Schottky Rectifier

### Features

- Low profile package
- Ideal for automated placement
- Guardring for overvoltage protection
- Low power losses, high efficiency
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

### DO-214AC (SMA)



### Typical Applications

For use in low voltage high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

### Mechanical Data

- **Package:** DO-214AC (SMA)  
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

### ■Maximum Ratings (T<sub>a</sub>=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	SS									
			22	23	24	25	26	28	210	215	220	
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	V	20	30	40	50	60	80	100	150	200	
Average Rectified Output Current @60Hz Half-sine wave, Resistance load, TL (FIG.1)	I <sub>O</sub>	A	2.0									
Surge(Non-repetitive)Forward Current @60Hz Half-sine wave, 1 cycle, T <sub>a</sub> =25°C	I <sub>FSM</sub>	A	50									
Junction Temperature	T <sub>j</sub>	°C	-55 ~+150					-55 ~+175				
Storage Temperature	T <sub>stg</sub>	°C	-55 ~+150									

### ■Electrical Characteristics (T<sub>a</sub>=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	SS							
				22	23	24	25	26	28	210	215
Maximum instantaneous forward voltage drop per diode	V <sub>F</sub>	V	I <sub>FM</sub> =2.0A	0.55		0.70		0.85		0.95	
Maximum DC reverse current at rated DC blocking voltage per diode@ V <sub>RM</sub> =V <sub>RRM</sub>	I <sub>RRM</sub>	mA	T <sub>a</sub> =25°C	0.50				0.10			
			T <sub>a</sub> =100°C	10				5			

■ Thermal Characteristics (T<sub>a</sub>=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	SS							
			22	23	24	25	26	28	210	215
Thermal Resistance	R <sub>θJ-A</sub> <sup>(1)</sup>	°C/W	75							
	R <sub>θJ-L</sub> <sup>(1)</sup>		17							

Note

(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

■ Characteristics (Typical)

